

## Process Change Notice

**Parts Affected:**

Chip processes CP192V(NPN) and CP592V(PNP), small signal discrete semiconductors, wafers, and die in chip form.

**Extent of Change:**

An overall reduction of the die area.

The CP192V chip process currently measures 13 x 17 mils and is being replaced by the CP392V chip process which measures 11 x 11 mils.

The CP592V chip process currently measures 12 x 20 mils and is being replaced by the CP792V chip process which measures 11 x 11 mils.

**Reason for Change:**

To accommodate assemblies of extremely small surface mount, epoxy molded packages.

**Effect of Change:**

This change does not affect the electrical characteristics of any device.

**Effective Date of Change:**

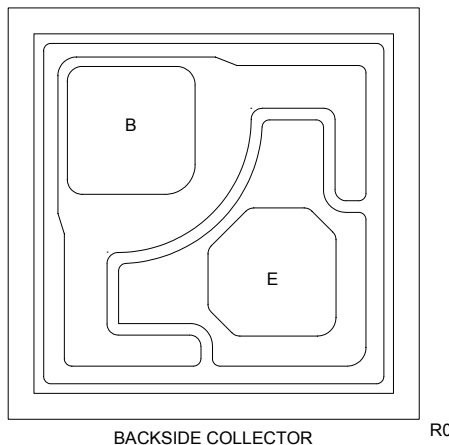
Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact Salesperson or Manufacturer's Representative.

**Figures:**

**CP392V / CP792V Chip Geometry**



Die Size: 11 x 11 mils  
Die Thickness: 7.1 mils  
Bond Pad Area (Base): 3.7 x 3.7 mils  
Bond Pad Area (Emitter): 3.7 x 3.7 mils

**PCN # 107**

**Notification Date:**

**29 June 2006**

**Part Numbers Affected:**

2N3904  
CMPT3904  
CMST3904  
CMUT3904  
CMXT3904  
CMXT3946  
CXT3904  
CZT3904  
MMPQ3904  
MMPQ6700  
MPQ3904  
MPQ6700  
CP192V-2N3904-WN  
CP192-CMPT3904-CT  
CP192-CMPT3904-WN

2N3906  
CMPT3906  
CMPT3906E  
CMST3906  
CMUT3906  
CMXT3906  
CMXT3946  
CXT3906  
CZT3906  
MMPQ3906  
MMPQ6700  
MPQ3906  
MPQ6700  
2N3251  
CP592-CEN1085-CT  
CP592-CEN1085-WN  
CP592-CMPT3906-CT  
CP592-CMPT3906-WN  
CP592-2N3251-CT  
CP592-2N3906-WN